



# Chip Design, [www.chipdesignmag.com](http://www.chipdesignmag.com) and *Chip Design* email newsletters reach over 100,000 design engineers and engineering managers working on advanced SoC designs.

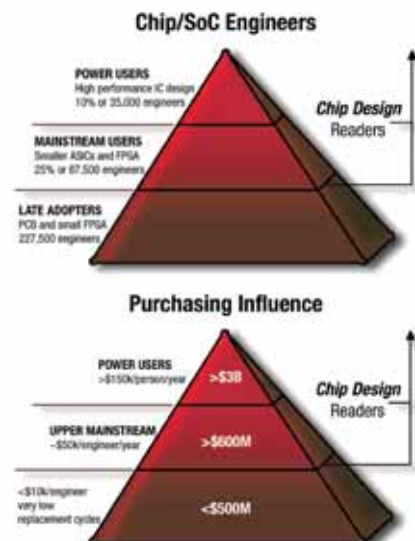
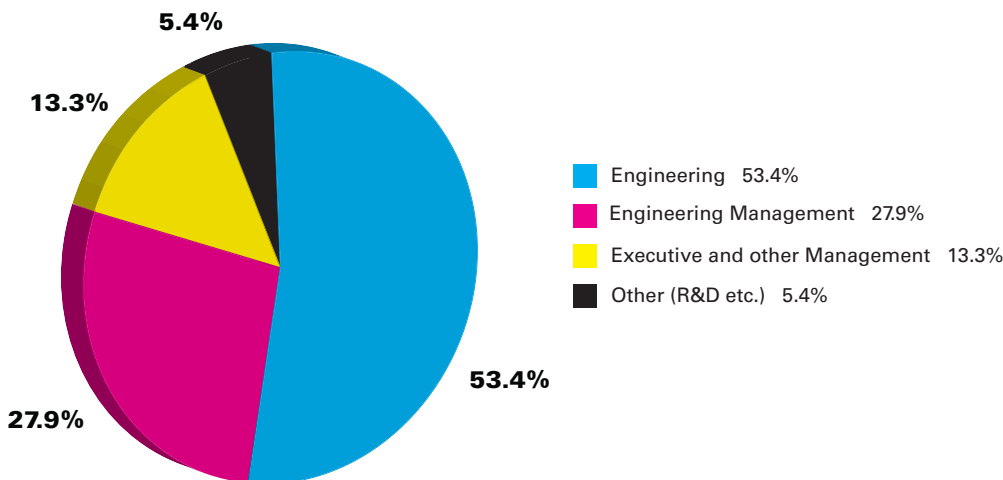
Chip Design's readers and [www.chipdesignmag.com](http://www.chipdesignmag.com) visitors are chip, programmable logic device and IP-related architects, designers, and testers. The readership also includes software protocol-application engineers and technical program managers. These architect-design-test engineers and managers are responsible for creating the latest generations of ASICs, structured ASIC, ASSPs, FPGAs, memory cores and SoC devices.

Circulation		
Average Monthly Visitors on <a href="http://www.chipdesignmag.com">www.chipdesignmag.com</a>	Magazine Readership	Email Newsletters Readership
<b>Page Views:</b> 237,598 <b>Visits:</b> 42,053 <b>Average Time on Site:</b> 48:31	<i>Chip Design Magazine</i> is distributed to over 40,000 qualified design engineers and engineering managers working on advanced SoC designs	⇨ <i>Chip Designer</i> is distributed to 32,011 subscribers ⇨ <i>IP Designer &amp; Integrator</i> is distributed to 28,214 subscribers ⇨ <i>FPGA &amp; PLD E-Product Alert</i> is distributed to 44,018 subscribers ⇨ <i>RF &amp; Microwave Systems</i> is distributed to 27,018 subscribers

## Powerful Purchasing Influence

System architect, design and test engineers and engineering managers working on advanced SoC designs—Chip Design readers—account for a third of all design engineers. These key enablers influence the purchase of nearly 80% of the total EDA market—or about \$4 billion.

### Circulation Breakdown by Job Responsibility



\*Source: Dataquest/Gartner

### Circulation Breakdown by Purchasing Responsibility

**94.8%**

Specify/Authorize/  
Influence the  
purchase of  
Design Automation  
tools and software

**80.6%**

Specify/Authorize/  
Influence the  
purchase of ASICs,  
FPGAs and PLDs

**70.1%**

Specify/Authorize/  
Influence the  
purchase of  
Intellectual  
Property

**52.9%**

Specify/Authorize/  
Influence the  
purchase of Standard  
ICs Services

**57.2%**

Specify/Authorize/  
Influence the purchase  
of Test Equipment/  
Development Tools

**35.6%**

Influence, specify  
or authorize the  
purchasing at  
companies with  
revenues of over  
\$500 million.

### Top 30 Subscribing Companies

Altera

AMD

Analog Devices

Atmel

Broadcom

Cisco

Cypress Semiconductor

Freescala

Fujitsu

GLOBALFOUNDRIES

Hewlett-Packard

IBM

IDT

Infineon

Intel

LSI

Marvell

Maxim Integrated Products

National Semiconductor

NVIDIA

NXP Semiconductors

ON Semiconductor

Oracle

PMC-Sierra

Qualcomm

Samsung Electronics

ST Microelectronics

Texas Instruments

VIA Technologies

Xilinx

# Chip Design Online Gateway Sponsorships Generate best ROI

## Market Leader Sponsorship

(limited to 2 sponsors)

### Marketing

- Logo on website identified as the Market Leader Sponsor
- 10,000 Leaderboard Banner Impressions Per Month
- Spotlight On Position with 3 links (above the fold, left hand column)
- Platinum Sponsor of one newsletter a month (486x60 banner +75 word text ad) sent out during your buy
- Add your blog to the Chip Design Featured Blog List

### Lead Generation

- Up to 3 lead generation enabled white papers
- Dedicated quarterly email blast to community subscriber list (25,000)

### Expanded Editorial Coverage

- Participation in content ticker below top navigation (your news headlines, article headlines, white paper headlines, viewpoint headlines, data sheet headlines run across content ticker)
- Unlimited Product Announcements
- Up to 3 videos featured on website
- One interview with Editor published on website and featured in email newsletter

**Price:** \$6,500 per month (6 month minimum)

## Platinum Sponsorship

(limited to 6 sponsors)

### Marketing

- Logo on website identified as the Platinum Sponsor
- 10,000 Large Rectangle Banner Impressions Per Month
- Gold Sponsor of one Email Newsletter (120x600 skyscraper banner +75 word text ad)
- Add your blog to the Chip Design Featured Blog List

### Lead Generation

- Up to 2 lead generation enabled white papers
- One Dedicated email blast to community subscriber list (25,000)

### Expanded Editorial Coverage

- Participation in content ticker below top navigation (your news headlines, article headlines, white paper headlines, viewpoint headlines, data sheet headlines will run across content ticker)
- Unlimited Product Announcements (we can use your RSS feeds)
- Up to 2 videos featured on website

**Price:** \$3,500 per month (6 month minimum)

## Website Marketing – Target the Chip Design Community



### Exclusive "Spotlight On" Position

High impact and above the fold, this position leverages your headlines to drive maximum visibility and traffic to your site  
Price - \$4,500 per month (6 month minimum)

### Exclusive Expandable Banner Showcase

High impact, center column position showcases your company as a market leader  
Price - \$3,500 per month (3 month minimum)

### Banners

- Skyscraper (125x600) - \$130 cpm
- Leaderboard (728x90) - \$130 cpm
- Large Rectangle (336x280) - \$130 cpm
- Banner Tiles (125x125) - \$40 cpm
- Standard Pop-Under (336x280) - \$350 cpm appears when browser closes
- Large Pop-Under (720x300) - \$450 cpm appears when browser closes

### Featured Videos/Blog

Each video or Blog is featured on ChipDesignMag.com and on EECatalog.com

- One video, 6 months - \$1,500
- One video, 12 months - \$2,000

### PR Maximizer (New)

Unlimited PR; 2 online datasheets/product briefs; rotating 125x125 banner \$850 or \$95 per month (6 month minimum; automatic renewal)  
Add on: One Print Product Showcase (\$1,500 total)

## High Quality Targeted Lead Generation Programs Deliver for Your Sales Team!



### White Paper Lead Generation Program

Submit your White Papers in PDF format and generate leads from the Chip Design market with these promos:

- Featured for 6 months on www.chipdesignmag.com and www.eecatalog.com
- Featured in Chip Designer and IP Designer & Integrator email newsletters that are broadcast monthly
- Showcased in 6 monthly Chip Design White Paper broadcasts
- \$1500 per White Paper -OR- \$3000 for 3 White Papers
- Dedicated email blast to 20,000 readers promoting your White Paper(s) for \$2500.

### Dedicated Email Blast

Send your own email blast to Chip Design subscriber lists

- \$300 cpm (15,000 minimum list size)

### Market Research and Lead Generation Program

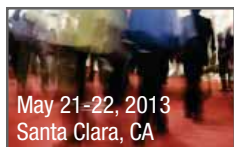
These programs enable sponsors to gain valuable market intelligence and generate leads with detailed demographics. Sponsor provides up to 15 questions. We provide a 4 page executive summary report, contact information on survey respondents.

- 80 guaranteed responses/leads. - \$7,500

### White Paper Editorial Development

- Our Editors will write your White Paper - \$7,500

## Events: 8th Annual Multicore Developers Conference



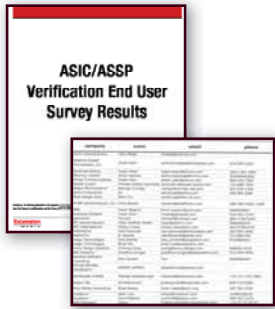
May 21-22, 2013  
Santa Clara, CA

The Only Combined Conference, Exhibition and Media Program Dedicated to the Deployment of Multicore and Virtualization Technology

- Two-day event with vetted presentations
- Directed by Industry Leading Analysts
- Before-During-After Marketing Impact
- Free Admittance to Qualified Registrants

Contact Sales Team  
for a  
Media Kit

# Gain Valuable Market Intelligence and Generate Leads with Detailed Demographics



## Market Research/Lead Generation Topics Include:

- EDA Tech & Tools (deadline: Feb 22)
- RF/Microwave Chip Design/Test (deadline: Mar 22)
- Verification (deadline: Sept 6)
- ASIC Prototyping (deadline: May 1)

## Sponsor benefits/opportunities include:

- Participation in creating survey questions
- Executive Summary and Analysis
- All research data
- Lead Generation - All contact data with detailed demographics
- Sponsor may add up to 3 proprietary questions (at an additional fee of \$2,500 per program)

Sponsor Fee: \$5,000

## Custom Research and Lead Generation Program

Gain valuable market intelligence and generate leads with detailed demographics. Sponsor provides up to 15 questions. We provide a 4 page executive summary report, contact information on survey respondents. 125 guaranteed responses/leads. ---- \$9,500

## Reach Targeted Audiences with Chip Design Email Newsletters



### Chip Designer e-Newsletter (Bi-monthly)

SoC digital and analog designers, system architects, IP integrators, DFM and verification engineers benefit from the latest news, viewpoints and technical articles. Covers such topics as ESL, IP, analog mixed signal, power, DFM-DFY, nanotechnology and more.



### FPGA & CPLD Quarterly Update e-newsletter

News and product solutions for FPGA and PLD system application engineers.



### IP Designer - Integrator e-Newsletter (Monthly)

Intellectual Property (IP) design and integration remains one of the hottest trends in the chip industry. Coverage includes trends in analog-digital, core-memory, design, verification, integration and qualification of IP in the SoC space.



### RF & Microwave Systems e-newsletter (Quarterly)

Trends, viewpoints, news and technical articles for design engineers and managers developing advanced RF and Microwave Systems designs

## Options

- **Exclusive Roadblock-- Limited to one Sponsor**
- 468x60 banner at top center position; side banner 125 x up to 728; up to three text ads; - \$6,000/issue
- **Platinum Sponsor**
- 468x90 banner at top center position and first text ad - \$2,500/issue
- **Gold Sponsor**
- Skyscraper top right banner position and second text ad - \$2,000/issue
- **Silver Sponsor**
- Second from top 125x125 banner position and third text ad - \$1,500/issue

## The #1 Magazine for the Advanced IC Design Market



Chip Design covers all of the technical challenges and implementation options that engineers face in the development and manufacture of today's complex integrated circuits (IC). Key focus areas includes the design of complex System-on-chips (SoCs), Electronic Design Automation (EDA) tools that enable SoC design and the semiconductor manufacturing process as it affects the design of SoCs including FPGAs and other programmable devices.

### Make sure you participate in the following 2012 Interoperability Guides:

- Spring (Foundry Ecosystems) • Fall (IP Interoperability) • Winter (Mentor Graphics)

### Sponsor or participate in:

- ➔ RF & Microwave Systems Special Issue (May release)
- ➔ Focus On: Design for Yield (July release)

## Options

- ➔ Full Page - \$3,500
- ➔ 2 Page Spread - \$5,000
- ➔ 1/2 Page - \$2,500
- ➔ Premium Positions - add 15%
- ➔ 1 Page Advertorial - \$1,500
- ➔ 2 Page Advertorial - \$2,500
- ➔ Full Page Product Showcase - \$1,000
- ➔ 1/2 Page Product Showcase - \$750

## Don't be left out of these important 2013 Annual Engineers' Guide Integrated Marketing Programs

Distributed in print, online and email newsletter formats each Resource Catalog is designed to help over 70,000 well-qualified engineers, embedded developers and chip designers make effective design and purchasing decisions all year long.



- ➔ Full Page Datasheet - \$1,250
- ➔ Additional Datasheet - \$1,000
- ➔ 2 Page Spread - \$2,950
- ➔ 1 Page 4/c - \$2,000
- ➔ Integrated Resource Catalog Marketing Sponsorships combine print, digital, website and email newsletter exposure. Prices range from \$7,500 to \$15,000 - ask for details.

## Marketing & Editorial Contacts

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### About Extension Media

Extension Media is a publisher of business-to-business magazines, resource catalogs and web sites that address high-technology industry platforms and emerging technologies such as embedded systems, chip design, intellectual property, software and infrastructure, architectures and operating systems.

# 2013 Editorial Calendar

Magazines, Special Issues, Webcasts, and Market Research & Lead Generation Programs

## Editorial Leadership

### John Blyler, Editorial Director

John is a leading authority on the technological issues that drive today's chip, advanced EDA and semiconductor industries.



He has worked in the electronics industry for over 25 years. Aside from editorial experience with the IEEE and technical trade journals, he has also co-authored books on systems-level design (IEEE-Wiley) and RF Design (Elsevier). John remains an affiliate professor in Systems Engineering at Portland State University.

### Ed Sperling, Consulting Editor

Ed is the Editor-in-Chief of the System-Level Design portal. He is the former Editor-in-Chief of Electronic News and Electronic Business.

### Mark LaPedus, Senior Editor

Mark has covered the semiconductor industry since 1986. He has held senior editorial positions at EE Times, Silicon Strategies, Electronic News and EBN. In Asia, he was a contributing writer for Byte Magazine.

### Cheryl Berglund Coupé, EECatalog.com Editor

Cheryl is editor of EECatalog.com and Embedded Intel® Solutions magazine. Cheryl's articles have appeared in EE Times, Electronic Business, Microsoft Embedded Review and Windows Developer's Journal and others.

### Jenn Burkhardt, Managing Editor

Jenn is the managing editor for Chip Designer, IP Designer and Chip Design magazine.

### Pallab Chatterjee, Regional Editor

Pallab is an long-time consultant, analyst and writer in the EDA, Mixed Signal and custom design space. He is president of Silicon Map.

### Dave Bursky, Senior Editor,

Dave is the former Editor-in-Chief of Penton's Electronic Design and editor at EETimes.

### Cheryl Ajluni, Contributing Editor

Cheryl is the former Editor-in-Chief for Wireless Systems Design. She is a patent-holding engineer with over 12 years experience covering the high-tech industry.

### Ann Steffora Mutschler, Contributing Editor

Ann has been a semiconductor editor and journalist for nearly two decades. Previously, she was a senior editor EDN, Electronic News and Electronic Business.

### Editorial Board

- Cheryl Ajluni, Consultant, Custom Media Solutions
- Karen Bartleson, Stds Manager, Synopsys
- Chuck Byers, Director Communications, TSMC
- Kathryn Kranen, CEO, Jasper Design Automation
- Tom Moxon, Consultant, Moxon Design
- Scott Sandler, CEO, Novas Software
- Steve Schulz, President, Si2
- Adam Traidman, Group Marketing Director, Chip Planning Solutions, Cadence Design Systems

## 2013 Chip Design Editorial Calendar

Issue	Focus Report/ Insert	Key Editorial Topics		Show Distribution	Ad Close	Materials Deadline
Winter	Mentor Graphics Partner Interoperability Guide	• Semiconductor • Processors • IP Modeling	• HW-SW CoDesign • Low Power	• DesignCon	Jan. 10	Jan. 14
Spring	Foundry Ecosystem Programs	• Low Power • Embedded Systems • 3D Integration	• IP Integration • Multicore	• DATE • ESC Silicon Valley	Feb. 25	Feb. 27
Summer	Resource Catalog	• RF-Wireless • Automotive • System Modeling • IP Integration	• MEMS • Semiconductor Manufacturing	• DAC • MTT-S • Semicon	May 14	May 17
Autumn	IP Ecosystem (ARM) Interoperability Guide	• DFM/DFY • SoC Design	• ASIC Proto - FPGA • Verification • Testing/Debug	• ARM TechCon • SoC Conference • ITC Test Conference	Sept. 23	Sept. 27
Winter	Mentor Graphics Partner Interoperability Guide	• Semiconductor • Processors • IP Modeling	• HW-SW CoDesign • Low Power	• DesignCon	Dec. 6	Dec. 10

## 2013 Special Issues

Issue	Key Editorial Topics		Show Distribution	Ad Close	Materials Deadline
RF & Microwave Systems - IMS 2013 Special Issue	• Analog • RF and Wireless • EDA Design Issues	• Manufacturing Challenges • Multi-die packaging	International Microwave Symposium	April 12	April 16
Focus On: Design for Yield	• Manufacturing Issues for the Latest Nodes • DFM-DFY	• IP Integration • MEMS	Semicon West	June 17	June 20

## Custom Content Marketing Solutions and Reprints from Chip Design



Hire the *Chip Design* Editorial and Marketing teams to produce and deliver valuable, relevant and compelling content for your customers and prospects on a consistent basis. Content marketing positions you as a trusted expert, impacts buying decisions, generates leads and improves SEO results! *All custom content may also be featured on www.chipdesignmag.com.*

- Articles or Case Study (2 to 4 pages)**
- 4 page: \$7,500
  - 2 page: \$4,500

**Branded Email Newsletters**  
Sent to combined list of your list and appropriate EECatalog subscribers (up to 40,000) and incorporating a featured article

- White Papers (8 to 10 pages) - \$9,500**
- Custom Blog**  
To appear on your website - will present brief chunks of valuable technology information and viewpoints related to your position in the market
- Monthly: \$2,000 per month
  - Weekly: \$6,000 per month

**Digital Magazines, print magazines, microsites, ebooks, social media add-ons quoted upon request**

**Reprints: Turn Chip Design print or online content into a powerful marketing piece and testimonial (print and online options)**  
- quote provided upon request

written by EECatalog Editor

- 12 month rate: \$6,500 per month
- Quarterly rate: \$7,500 per issue

**Featured in Editorial Video (less than 10 minutes)**  
\$3,000 (does not include travel if required)

# 2013 Editorial Calendar

Newsletters  
and Resource Catalogs

## Chip Design Email Newsletter Editorial Calendar

### Chip Designer newsletter

Issue	Feature Topic	Ad Close	Materials	Issue	Feature Topic	Ad Close	Materials
January	• Power	Jan 11	Jan 14	July	• Green Design	Jul 10	Jul 12
	• FPGA-Board	Jan 23	Jan 25		• Trends	Jul 24	Jul 26
February	• SoC Design	Feb 6	Feb 8	August	• IP Challenges	Aug 7	Aug 9
	• Multicore Issues	Feb 20	Feb 22		• Package Issues	Aug 21	Aug 23
March	• Multicore Design	Mar 8	Mar 11	September	• Lithography	Sep 4	Sep 6
	• Stacked Die	Mar 22	Mar 25		• Bonding Issues	Sep 18	Sep 20
April	• IP Integration	Apr 5	Apr 8	October	• Advanced Chip Verification	Oct 9	Oct 11
	• Interconnect	Apr 19	Apr 22		• Verification IP	Oct 23	Oct 25
May	• Programmable HW	May 8	May 10	November	• Design-for-Manufacturability	Nov 1	Nov 4
	• Analog-Wireless	May 22	May 24		• Interface IP	Nov 13	Nov 15
June	• Analog-RF-Wireless	Jun 5	Jun 7	December	• Design-for-Yield	Dec 2	Dec 3
	• IP Integration	Jun 19	Jun 21		• System Trends	Dec 12	Dec 13

### IP Designer & Integrator newsletter

Issue	Feature Topic	Ad Close	Materials	Issue	Feature Topic	Ad Close	Materials
January	IP Trends	Jan 16	Jan 18	July	Memory IP	Jul 17	Jul 19
February	Core IP	Feb 13	Feb 15	August	Interface IP - Wireless	Aug 14	Aug 16
March	Interface IP	Mar 12	Mar 14	September	Interconnect IP	Sept 11	Sept 13
April	IP Standards	Apr 10	Apr 12	October	Low Power IP	Oct 16	Oct 18
May	Analog Wireless	May 15	May 17	November	Interface IP	Nov 6	Nov 8
June	IP Metrics	Jun 12	Jun 14	December	Verification IP	Dec 4	Dec 6

### FPGA & CPLD Quarterly Update Newsletter

Issue	Ad Close	Materials	Issue	Ad Close	Materials
Q1	Feb 1	Feb 4	Q3	Aug 1	Aug 5
Q2	May 1	May 3	Q4	Oct 30	Nov 1

### RF & Microwave Systems

Issue	Ad Close	Materials	Issue	Ad Close	Materials
Q1	Feb 26	Feb 28	Q3	Aug 1	Aug 5
Q2	May 10	May 13	Q4	Nov 21	Nov 25

### 2013 Annual Engineers' Guide Editorial Calendar

Market Focus	Pub Date	Space Deadline	Materials Deadline	Targeted Reach	Bonus Distribution
Low Power System Design	March	March 5	March 8	Designers and engineers working on low power and power efficient designs	Design West
Multicore and Virtualization Technologies	May	April 29	May 2	Developers and engineers using multicore and multiprocessing designs	Design West, Multicore DevCon
Engineers' Guide to Sensors and MEMS Design	May	May 10	May 14	Designers and engineers working with embedded sensors, MEMS and related technologies	Sensor Expo
Chip Design Engineers' Guide	June	May 15	May 21	Advanced IC designers	DAC
PCI Express	October	October 10	October 15	Engineers and embedded developers using or considering PCI Express solutions	DesignCon
FPGA and PLD Solutions	November	November 26	November 30	FPGA and PLD system application engineers	DesignCon, DAC

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#### About Extension Media

Extension Media is a publisher of business-to-business magazines, resource catalogs and web sites that address high-technology industry platforms and emerging technologies such as embedded systems, chip design, intellectual property, software and infrastructure, architectures and operating systems.